EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S64	6	("5027191"|"6483187"|"6525942").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S65	4	("6020629"|"6528882").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S66	10	("4835598" | "5130771" | "5640048" | "5959356" | "6206997" | "6282094" | "6325272").PN. OR ("6528882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S67	31	("5285352" | "5583377" | "5642261" | "5741729" | "5825628" | "5942795" | "5959356" | "6008536" | "6023098" | "6034427" | "6038137" | "6117705" | "6125042").PN. OR ("6282094"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S68	9	("5027191" | "5710459" | "5741729" | "6212076" | "6282094" | "6483187" | "6525942" | "6657864" | "6882537").PN. OR ("6954360"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S69	6	S68 not S64	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S70	9	("5027191" | "5710459" | "5741729" | "6212076" | "6282094" | "6483187" | "6525942" | "6657864" | "6882537").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S71	0	(3061/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S72	2899	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S73	120	S72 and die with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

S74	540	(257/670).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S75	18101	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S76	50	S74 and pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S77	9733	(257/66$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S78	328	S77 and pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S79	304	S78 not S76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S80	246	S78 not S76	USPAT	OR	ON	2006/11/10 15:11
S81	74	("5479050" | "5594234" | "5663597").PN. OR ("6211462"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S82	8832	(257/67$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S83	365	S82 and pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

S84	191	S83 not S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S85	18101	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S86	11870	pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S87	8832	S82 S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S88	365	S87 and S86	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S89	0	S88 not (S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S90	7641	pad near5 tip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S91	747	S90 and S86	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S92	716	S91 not (S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

S93	6755	S90 not S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S94	176	S87 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S95	176	S94 not (S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S96	2546	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near5 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S97	2147	S96 not S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S98	2169	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S99	1818	S98 not S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S100	685	(IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (extend$3 attach$3 prolong$3) with (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S101	15246	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

S102	272	S100 and S101	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S103	216	S102 not (S84 S81 S79 S78 S95)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S104	139	S102 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S105	108	S104 not (S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S106	503	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S107	388	S106 not (S103 S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S108	1	S104 and S107	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S109	86	S107 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S110	1419	((IC chip die integrated near1 circuit semiconductor siliocn) with pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S111	879	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

S11 2	1866277	((IC chip die integrated near1 circuit semiconductor siliocn) near1pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 3	600	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 4	388	S113 not S107	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 5	78	S113 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 6	12	("4362899" | "4890155" | "5194833").PN. OR ("5373187"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S11 7	199	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 8	0	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 9	26	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S12 0	28	("4551746" | "4551747" | "5089881" | "5218230" | "5513076").PN. OR ("5691568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S12 1	76	("5519576" | "5672909" | "5691568").PN. OR ("5903050"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11

| S12 2 | 297 | ("20010008305" \| "20010014538" \| "20020011654" \| "20020027297" \| "20020140061" \| "20020140068" \| "20020163015" \| "20030030131" \| "20030073265" \| "2596993" \| "3435815" \| "3734660" \| "3838984" \| "4054238" \| "4189342" \| "4258381" \| "4289922" \| "4301464" \| "4332537" \| "4417266" \| "4451224" \| "4530152" \| "4541003" \| "4646710" \| "4707724" \| "4727633" \| "4737839" \| "4756080" \| "4812896" \| "4862245" \| "4862246" \| "4907067" \| "4916519" \| "4920074" \| "4935803" \| "4942454" \| "4987475" \| "5018003" \| "5029386" \| "5041902" \| "5057900" \| "5059379" \| "5065223" \| "5070039" \| "5087961" \| "5091341" \| "5096852" \| "5118298" \| "5151039" \| "5157475" \| "5157480" \| "5168368" \| "5172213" \| "5172214" \| "5175060" \| "5200362" \| "5200809" \| "5214845" \| "5216278" \| "5218231" \| "5221642" \| "5250841" \| "5252853" \| "5258094" \| "5266834" \| "5273938" \| "5277972" \| "5278446" \| "5279029" \| "5281849" \| "5294897" \| "5327008" \| "5332864" \| "5335771" \| "5336931" \| "5343076" \| "5358905" \| "5365106" \| "5381042" \| "5391439" \| "5406124" \| "5410180" \| "5414299" \| "5424576" \| "5428248" \| "5435057" \| "5444301" \| "5452511" \| "5454905" \| "5474958" \| "5484274" \| "5493151" \| "5508556" \| "5517056" \| "5521429" \| "5528076" \| "5534467" \| "5539251" \| "5543657" \| "5544412" \| "5545923" \| "5581122" \| "5592019" \| "5592025" \| "5594274" \| "5595934" \| "5604376" \| "5608265" \| "5608267" \| "5625222" \| "5633528" \| "5639990" \| "5640047" \| "5641997" \| "5643433" \| "5644169" \| "5646831" \| "5650663" \| "5661088" \| "5663593" \| "5665996" \| "5673479").PN. OR ("5683806" \| "5689135" \| "5696666" \| "5701034" \| "5703407" \| "5710064" \| "5723899" \| "5724233" \| "5726493" \| "5736432" \| "5745984" \| "5753532" \| "5753977" \| "5766972" \| "5770888" \| "5776798" \| "5783861" \| "5801440" \| "5814877" \| "5814881" \| "5814883" \| "5814884" \| "5817540" \| "5818105" \| "5821457" \| "5821615" \| "5834830" \| "5835988" \| "5844306" \| "5856911" \| "5859471" \| "5866939" \| "5871782" \| "5874784" \| "5877043" \| "5886397" \| "5886398" \| "5894108" \| "5897339" \| "5900676" \| "5903049" \| "5903050" \| "5909053" \| "5915998" \| "5917242" \| "5939779" \| "5942794" \| "5951305" \| "5959356" \| "5969426" \| "5973388" \| "5976912" \| "5977613" \| "5977615" \| "5977630" \| "5984314" \| "5986333" \| "5986885" \| "6001671" \| "6013947" \| "6018189" \| | US-PGPUB; USPAT; USOCR | OR | ON | 2006/11/10 15:11 |

S12 3	1	"5594234".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S12 4	30	("4714952" | "5252783" | "5428248" | "5436500" | "5440170").PN. OR ("5594234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S12 5	2487	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S12 6	1447	(257/691).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S12 7	1476	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:34

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1476	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:37
L2	120	1 and finger with die near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:51
L3	492	((pad electrode contact land) and (encomps$5 encircl$4 enclos$4 surround$4) and ((IC chip die integrated near1 cicuit wafer die semiconductor silicon) near1 pad)). clm.	US-PGPUB	OR	ON	2006/11/10 15:56
L4	16	((pad electrode contact land) and (finger falange) and (encomps$5 encircl$4 enclos$4 surround$4) and ((IC chip die integrated near1 cicuit wafer die semiconductor silicon) near1 pad)).clm.	US-PGPUB	OR	ON	2006/11/10 15:57
L5	291	((pad electrode contact land) and (finger falange layer film) and (encomps$5 encircl$4 enclos$4 surround$4) and ((IC chip die integrated near1 cicuit wafer die semiconductor silicon) near1 pad)). clm.	US-PGPUB	OR	ON	2006/11/10 15:57